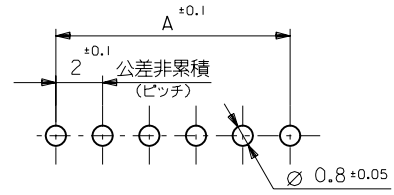


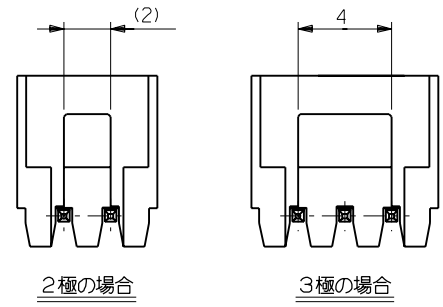
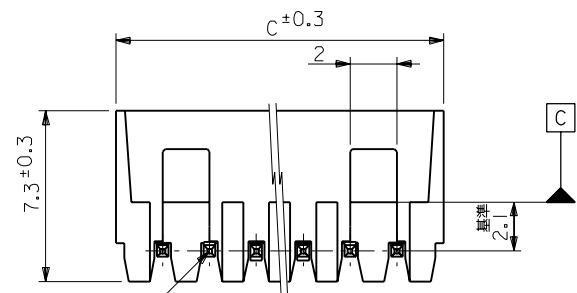
注記

1 炭合相手：51065-***00
 △ キンクは下記表の位置及び形状に付加のこと。 2極はキンク無し。

回路番号	1	2	3	4	5	N-2	N-1	N
極数								
6 極以上	—	①	②	—	—	②	①	—
5 極	①	②	—	②	①			
4 極	①	②	②	①				
3 極	①	②	①					



基板取付寸法 (参考)
(t = 1.6)



0.8 C D

32	31.1	28	53254-1510	15
30	29.1	26	-1410	14
28	27.1	24	-1310	13
26	25.1	22	-1210	12
24	23.1	20	-1110	11
22	21.1	18	-1010	10
20	19.1	16	-0910	9
18	17.1	14	-0810	8
16	15.1	12	-0710	7
14	13.1	10	-0610	6
12	11.1	8	-0510	5
10	9.1	6	-0410	4
8	7.1	4	-0310	3
6	5.1	2	53254-0210	2
C	B	A	ENG NO.	極数

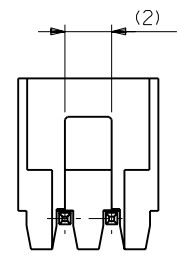
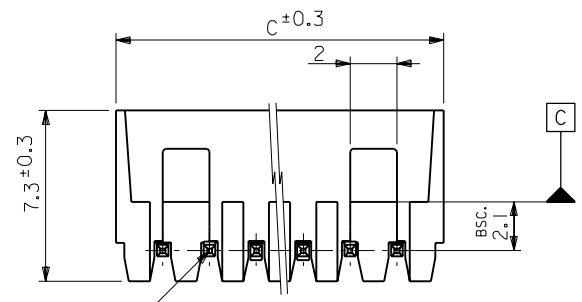
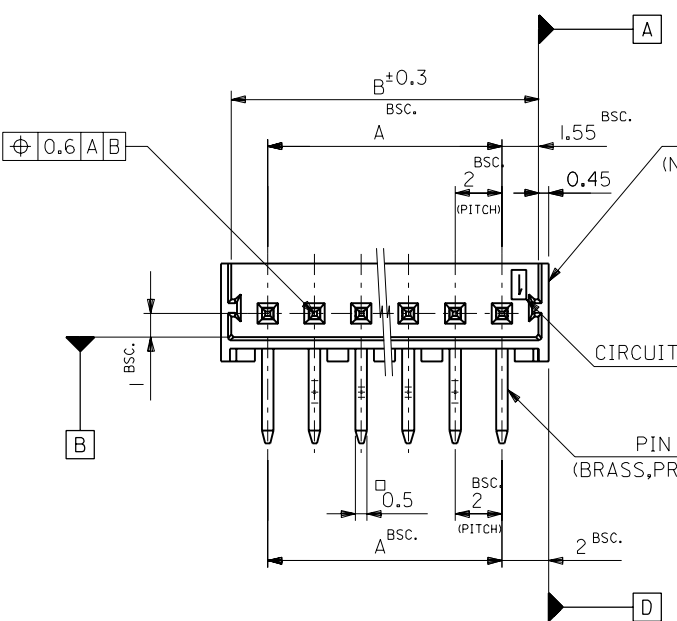
角度 ANGLE	±3°				材料 MATERIAL	図中参照	molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
30以上 OVER	+0.3				仕上げ FINISH	図中参照	
10以上 30未滿 UNDER	+0.25				適用電線範囲 WIRE RANGE	— / —	ENG. NO.
10未滿 UNDER	+0.2				被覆外径 INS. RANGE	— / —	SD-53254-***10
一般公差 GENERAL TOLERANCES					DRAWN BY '89/9/21	CHK'D BY '91/03/09	REV C
					S.AIHARA	M.MUKUSHIMA	TITLE 名称
					APPR'D BY '91/03/09	M.MUKUSHIMA	NEW 2.0 WIRE TO BOARD CONN. WAFER ASS'Y (R/A)
					DR. DATE	尺度 SCALE	5-1
					REVISION RECORD		
					REVISION RECORD		
					REVISION RECORD		
					REVISION RECORD		

ENG. NO.
SD-53254-***10

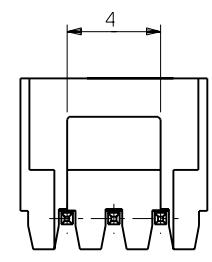
EDP. NO.

:MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING

8 7 6 5 4 3 2 1



IN CASE OF
2 CIRCUIT WAFER

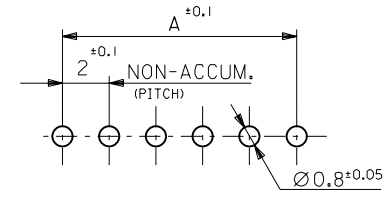


IN CASE OF
3 CIRCUIT WAFER

NOTES

1 MATES WITH :51065-***00
 △KINK TO BE APPLIED AS FOLLOWS, 2 CIRCUIT HAS NO KINK

CKT NO.	1	2	3	4	5	N-2	N-1	N
MORE THAN 6 CKT	—	①	②	—	—	②	①	—
5 CKT	①	②	—	②	①	—	—	—
4 CKT	①	②	②	①	—	—	—	—
3 CKT	①	②	①	—	—	—	—	—



RECOMMENDED P.C. BOARD HOLE DIMENSION (REFERENCE)
 (t = 1.6)

32	31.1	28	53254-1510	15
30	29.1	26	-1410	14
28	27.1	24	-1310	13
26	25.1	22	-1210	12
24	23.1	20	-1110	11
22	21.1	18	-1010	10
20	19.1	16	-0910	9
18	17.1	14	-0810	8
16	15.1	12	-0710	7
14	13.1	10	-0610	6
12	11.1	8	-0510	5
10	9.1	6	-0410	4
8	7.1	4	-0310	3
6	5.1	2	53254-0210	2
C	B	A	ENG NO.	CKT

角度 ANGLE	公差 TOL.	記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE
30 以上 OVER	+3°				
10 以上 30 未満 UNDER	+0.3				
10 未満 UNDER	+0.2				
一般公差 GENERAL TOLERANCES					

材料 MATERIAL	REFER TO DRAWING
仕上げ FINISH	REFER TO DRAWING
適用電線範囲 WIRE RANGE	—
被覆外径 INS. RANGE	—
DRAWN BY '89/9/21 S.AIHARA	CHK'D BY '91/3/11 M.MURAKUSHIMA
APP'D BY '91/3/11 M.MURAKUSHIMA	SCALE 5-1

材料 MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
EDP. NO.	
ENG. NO. SD-53254-***10	REV C
TITLE 名称 NEW 2.0 WIRE TO BOARD CONN. WAFER ASS'Y (R/A)	

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